

ABSTRACT OF THE DISCLOSURE

A board for printed wiring comprises an electromagnetic wave absorbing laminate (EM) provided on a surface of a substrate (1) with the intervention 5 of an adhesive layer (2) of a metal oxide, the electromagnetic wave absorbing laminate (EM) comprising: (a) a magnetic layer (3) comprising a plurality of magnetic particles (31) having an average particle diameter of 1 to 150 nm and isolated from each other by an electrically 10 insulative material (32); and (b) an electrically insulative layer (4), being alternately stacked in a multi-layer structure, the board for printed wiring has a reduced thickness and an improved electromagnetic wave absorbing characteristic in a high frequency band of not 15 lower than gigahertz, as compared with a conventional one which has an electromagnetic wave absorbing layer of a composite material including fine magnetic particles simply dispersed in a resin binder.